

Description

Tokmas Power MOSFET is fabricated using advanced super junction technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

Features

- ◆ Ultra low $R_{DS(on)}$
- ◆ Ultra low gate charge (typ. $Q_g = 39nC$)
- ◆ 100% UIS tested
- ◆ RoHS compliant

Applications

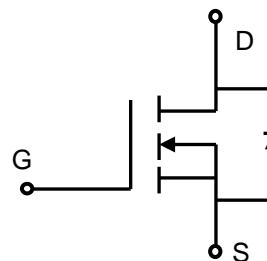
- ◆ Power factor correction (PFC).
- ◆ Switched mode power supplies (SMPS).
- ◆ Uninterruptible power supply (UPS).

Product Summary

$V_{DS} @ T_{j,max}$	700V
$R_{DS(on),max}$	0.18Ω
I_{DM}	60A
$Q_{g,typ}$	39nC



TO-220MF



N-Channel MOSFET



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	650	V
Continuous drain current ($T_C = 25^\circ C$)	I_D	20	A
($T_C = 100^\circ C$)		13	A
Pulsed drain current ¹⁾	I_{DM}	60	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ²⁾	E_{AS}	600	mJ
Avalanche energy, repetitive ³⁾	E_{AR}	0.4	mJ
Avalanche current, repetitive ³⁾	I_{AR}	20	A
Power Dissipation TO-247 ($T_C = 25^\circ C$)	P_D	34	W
- Derate above $25^\circ C$		0.28	W/ $^\circ C$
Mounting torque To-220MF (M2.5 screws)		50	Ncm
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$
Continuous diode forward current	I_S	20	A
Diode pulse current	$I_{S,pulse}$	60	A

Thermal Characteristics TO-220MF

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.6	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	80	$^\circ C/W$



Super Junction Power MOSFET

CI20N65F

Electrical Characteristics

T_c = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =0.25 mA	650	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =0.25mA	2	3.5	5	V
Drain cut-off current	I _{DSS}	V _{DS} =650 V, V _{GS} =0 V, T _j = 25°C T _j = 125°C	-	-	1	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =30 V, V _{DS} =0 V	-	-	50	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-30 V, V _{DS} =0 V	-	-	-50	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =10 A T _j = 25°C T _j = 150°C	-	0.16	0.18	Ω
Gate resistance	R _G	f=1 MHz, open drain	-	4.4	-	Ω
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	2637	-	pF
Output capacitance	C _{oss}		-	1250	-	
Reverse transfer capacitance	C _{rss}		-	17	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 380V, I _D = 10A R _G = 4.7Ω, V _{GS} =10V	-	23	-	ns
Rise time	t _r		-	33	-	
Turn-off delay time	t _{d(off)}		-	113	-	
Fall time	t _f		-	11	-	
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DD} =480 V, I _D =10A, V _{GS} =0 to 10 V	-	10.3	-	nC
Gate to drain charge	Q _{gd}		-	13.7	-	
Gate charge total	Q _g		-	39	-	
Gate plateau voltage	V _{plateau}		-	5.5	-	V
Reverse diode characteristics						
Diode forward voltage	V _{SD}	V _{GS} =0 V, I _F =10A	-	1.0	-	V
Reverse recovery time	t _{rr}	V _R =50 V, I _F =20A, dI _F /dt=100 A/μs	-	390	-	ns
Reverse recovery charge	Q _{rr}		-	3.6	-	μC
Peak reverse recovery current	I _{rrm}		-	18	-	A

Notes:

- Limited by maximum junction temperature, maximum duty cycle is 0.75.
- I_{AS} = 5A, V_{DD} =60V, Starting T_j= 25°C.
- Repetitive Rating: Pulse width limited by maximum junction temperature.

Electrical Characteristics Diagrams

Figure 1. On-Region Characteristics

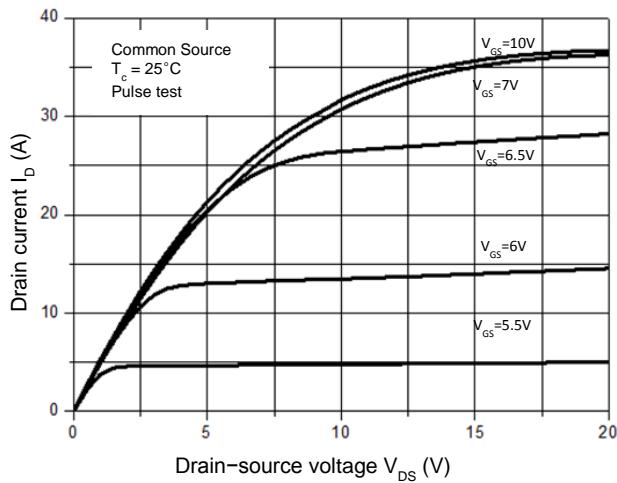


Figure 2. Transfer Characteristics

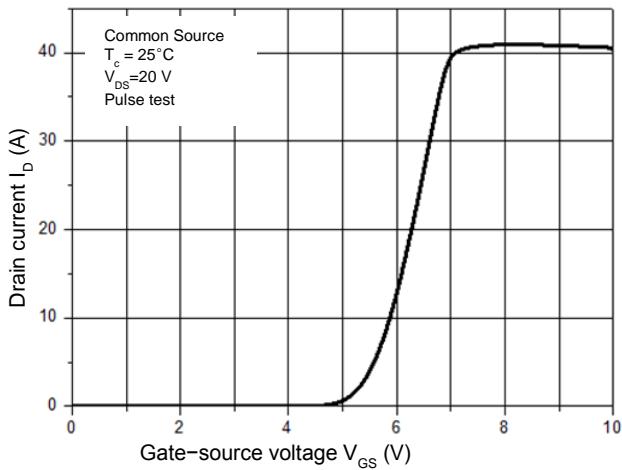


Figure 3. On-Resistance Variation vs. Drain Current

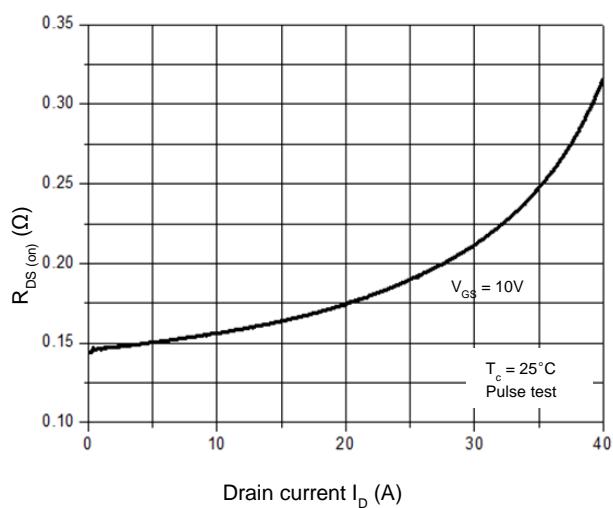


Figure 4. Threshold Voltage vs. Temperature

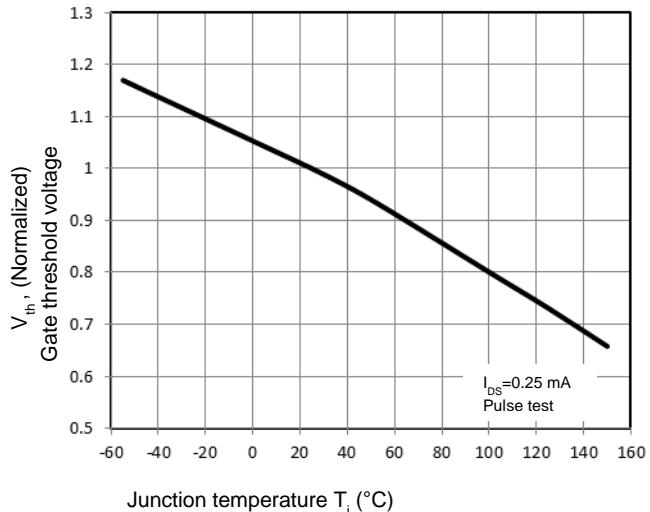


Figure 5. Breakdown Voltage vs. Temperature

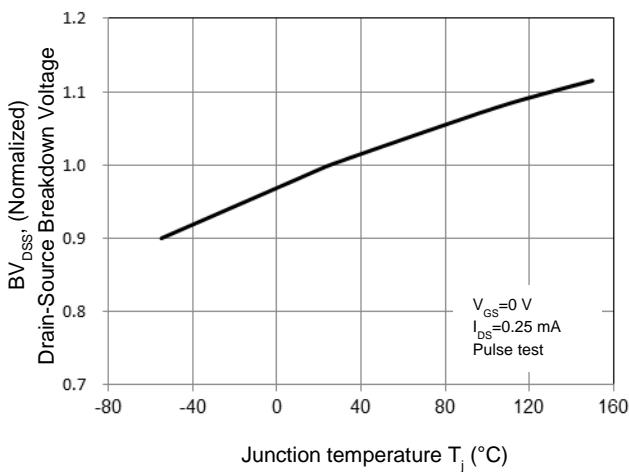


Figure 6. On-Resistance vs. Temperature

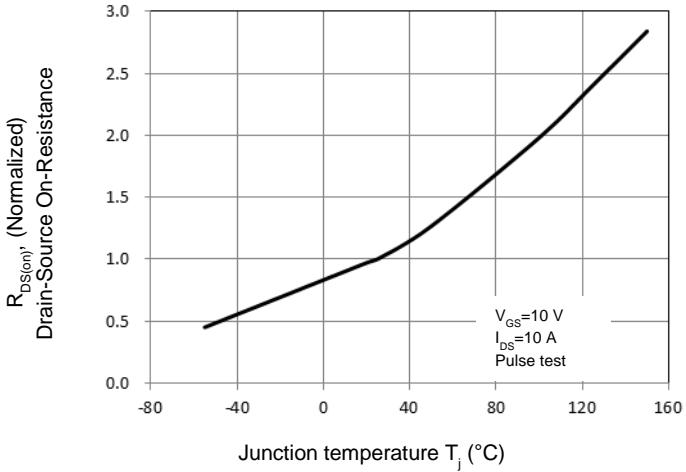
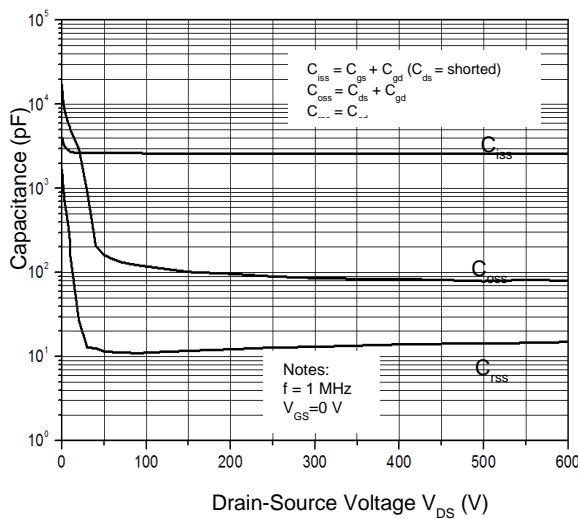
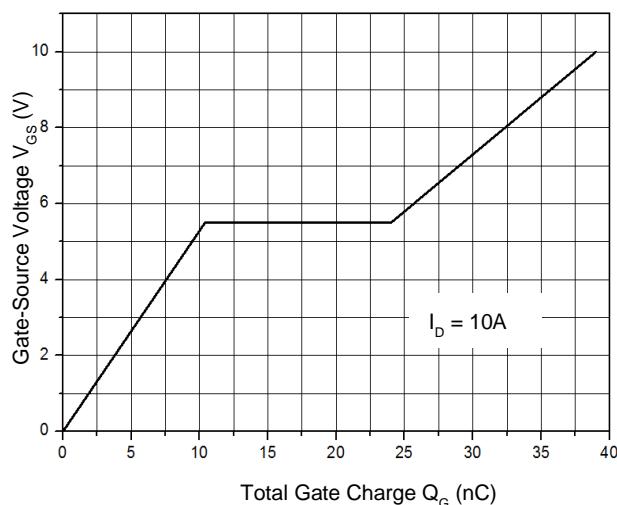
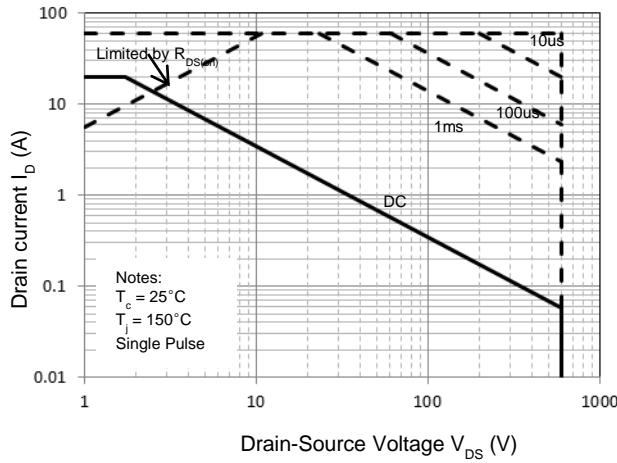
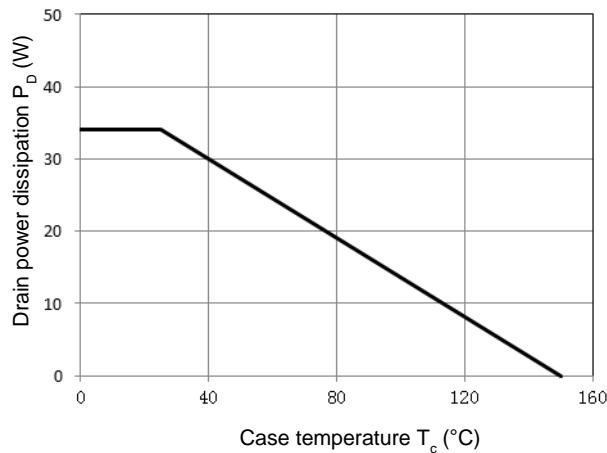
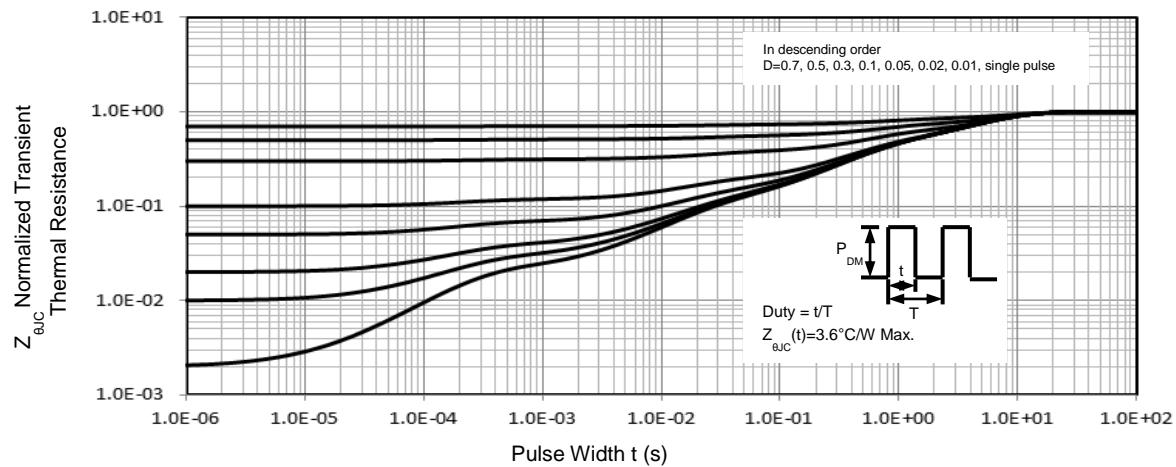
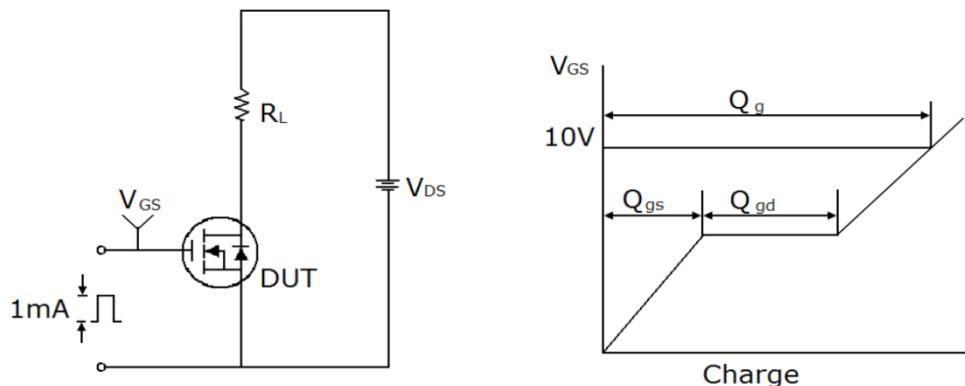
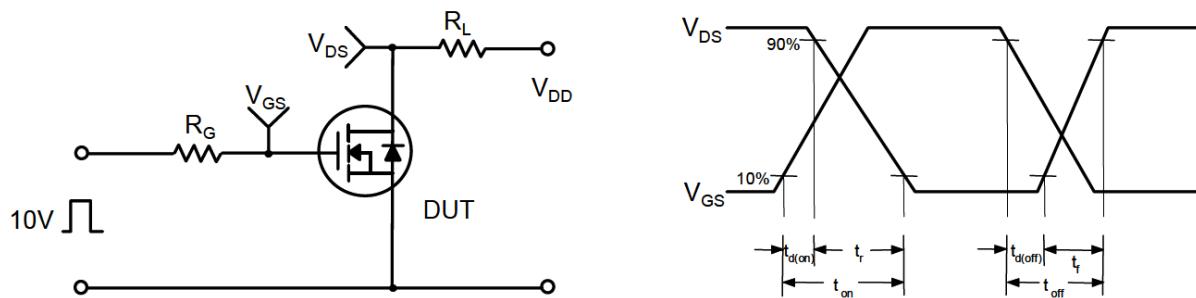


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characterist

Figure 9. Maximum Safe Operating Area

Figure 10. Power Dissipation vs. Temperature

Figure 11. Transient Thermal Response Curve


Gate Charge Test Circuit & Waveform

Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms
